



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: I-0210-02 DATE: 10/28/02
Product Affected: 79RC32V332, 79RC32V334

MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark
- Back Mark N/A
- Date Code
- Other

Date Effective: 10/28/2002

Contact: Bimla Paul
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Attachment: Yes No

Samples: N/A

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other

To add a new parameter, cpu_coldreset_n Rise Time (t_{CRRise}) to Table 5 - Clock Parameters to clarify the device application conditions as follow:

Parameter	Symbol	All Speed grades
cpu_coldreset_n Rise Time	t_{CRRise}	5 ns (Max)

This is a data sheet change only.
The latest data sheet can be viewed at IDT web site:
http://www.idt.com/products/pages/Integrated_Processors.html

RELIABILITY/QUALIFICATION SUMMARY:

N/A

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

Approval for shipments prior to effective date.

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____